

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	861	(wafer or semiconductor or substrate) and dielectric and (open or via or hole or trench) and scribe and die and (metal or conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:02
S2	872	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and scribe and die and (metal or conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:02
S3	414	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and scribe and die and (metal or conduct\$4) and stress	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:02
S4	336	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and scribe and die and (metal or conduct\$4) and stress and plurality	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:02
S5	272	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and scribe and die and (metal or conduct\$4) and stress and plurality and expos\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:03
S6	206	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and scribe and die and (metal or conduct\$4) and stress and plurality and expos\$3 and region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:03
S7	27	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and scribe and die and (metal or conduct\$4) and stress and plurality and expos\$3 and region and pit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:19
S8	6	die and "scribe line" and (wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and (metal or conduct\$4) and pit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 08:24

S9	43	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and (metal or conduct\$4) and pit and "scribe line"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 12:59
S10	6	(wafer or semiconductor or substrate) and dielectric and (opening or via or hole or trench) and (metal or conduct\$4) and pit and "scribe line" and die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 12:59